

PACKAGE: MLP8 2.0 x 2.0 (GREEN)

MATERIALS DECLARATION:

No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element Wt (%)	Element Wt (mg)	Wt % Of Total Unit Wt	ppm
1	Leadframe	Copper A194 PEH	0.7722	Cu	7440-50-8	97.5	0.7529	32.9495	329494.67
				Fe	7439-89-6	2.35	0.0181	0.7942	7941.67
				Zn	7440-66-6	0.12	0.0009	0.0406	405.53
				P	7723-14-0	0.03	0.0002	0.0101	101.38
2	Die attach material	Screen print 8006NS	0.0199	Aluminium Oxide	1344-28-1	50	0.0099	0.4352	4352.04
				2-(2-Ethoxyetho	112-15-2	20	0.0040	0.1741	1740.82
				Phenol, 4,4'-(1-methylethylidene	25036-25-3	20	0.0040	0.1741	1740.82
				Epoxy resin	25068-38-6	5	0.0010	0.0435	435.20
				Aromatic Amine	Proprietary	5	0.0010	0.0435	435.20
3	Gold Wire	Gold	0.0147	Au	7440-57-5	99.99	0.0147	0.6443	6442.78
				Others	Proprietary	0.01	0.0000	0.0001	0.64
4	Internal Plating	NiPdAu	0.0049	Ni	7440-02-0	92.23	0.00450	0.1970	1969.63
				Pd	7440-05-3	7.47	0.00036	0.0160	159.57
				Au	7440-57-5	0.30	0.00001	0.0006	6.41
5	External Plating	NiPdAu	0.0065	Ni	7440-02-0	92.23	0.0060	0.2611	2610.91
				Pd	7440-05-3	7.47	0.0005	0.0212	211.52
				Au	7440-57-5	0.30	0.00002	0.0008	8.50
6	Mold Compound	EME G770HCD	1.2963	Silica Fused	60676-86-0	91.7	1.1888	52.0258	520257.89
				Epoxy Resin	Trade secret	4	0.0519	2.2694	22693.91
				Phenol Resin	Trade secret	4	0.0519	2.2694	22693.91
				Carbon Black	1333-86-4	0.3	0.0039	0.1702	1702.04
7	Die	Silicon Die	0.1704				0.1704	7.4595	74594.94
Total unit weight =			2.2849						

REVISION HISTORY

Revision	Date	Description
A	3/4/2014	Initial Release